

11-13-2002

FORM PTO-1595

(Rev. 6-93)

REC



HEET

U.S. DEPARTMENT OF COMMERCE  
Patent and Trademark Office

OMB No. 0651-0011 (exp. 4/94)

Tab settings

102279082

To the Assistant Commissioner for Patents:  
Please record the attached original documents or copy thereof.

11/05/02  
29/170358  
JC973 U.S. PTO

1. Name of conveying party(ies):

Jang Hyuk AHN

11/05/02

Additional name(s) of conveying party(ies) attached?  Yes  No

3. Nature of conveyance:

- Assignment
- Merger
- Security Agreement
- Change of Name
- Other \_\_\_\_\_

Execution Date: October 29, 2002

2. Name and address of receiving party(ies)

Name: EHWA DIAMOND INDUSTRIAL CO., LTD.

Street Address: 520-2 Wondong, Osan,

Kyungki-do, Republic of Korea

Additional name(s) & address(es) attached?  Yes  No

4. Application number(s) or patent number(s):

29/170358

If this document is being filed together with a new application,  
the execution date of the application is: October 29, 2002

A. Patent Application No. (s)

B. Patent No. (s)

Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Kent E. Baldauf, Sr.

Internal Address: Webb Ziesenheim Logsdon

Orkin & Hanson, P.C.

Street Address: 700 Koppers Building

436 Seventh Avenue

City: Pittsburgh State: PA ZIP: 15219-1818

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41).....\$ 40.00

Enclosed

Authorized to be charged to deposit account

8. Deposit account number:

(Attach triplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Kent E. Baldauf, Sr., Reg. No. 25,826

Name of Person Signing

*Kent E. Baldauf*  
Signature

November 5, 2002

Date

Total number of pages including cover sheet, attachments and document 3

Mail documents to be recorded with required cover sheet information to:  
Assistant Commissioner for Patents, U.S. Patent and Trademark Office  
Office of Public Records, Crystal Gateway 4, Room 335  
Washington, D.C. 20231

11/07/2002 DEMANDU1 00000098 29170358

40.00 OF

02 FC:8021 (W0028082.1)

PATENT  
REEL: 013470 FRAME: 0281

## ASSIGNMENT

WHEREAS, I, Jang Hyuk AHN residing in 101-1402 Hyundai Apt., 922-2 Osan-dong, Osan, Kyungki-do, Republic of Korea; have invented certain new and useful improvements entitled **TIP FOR CORE DRILL** for which I have this day executed an application for United States Letters Patent;

AND, WHEREAS **EHWA DIAMOND INDUSTRIAL CO., LTD.**, a corporation of the Republic of Korea, having a place of business at 520-2 Wondong, Osan, Kyungki-do, Republic of Korea hereinafter called the "assignee", are desirous of acquiring the entire right, title, and interest in and to said application and the inventions and improvements therein disclosed.

NOW, THEREFORE, in consideration of One (\$1.00) Dollar and other good and valuable consideration paid to me by said assignee, the receipt of which is hereby acknowledged, I do hereby assign, sell, transfer, and set over unto said assignee the entire right, title and interest in and to said application and the inventions and improvements therein disclosed for the United States and all foreign countries and any Letters Patent which may issue therefor in the United States and all foreign countries and all divisions, reissues, continuations, renewals, and/or extensions thereof, said assignee to have and to hold the interests herein assigned to the full ends of the terms of said Letters Patent and any and all divisions, reissues, continuations, renewals, and/or extensions thereof, respectively, as fully and entirely as the same would have been held and enjoyed by me had this assignment not been made.

The Commissioner of Patents and Trademarks is requested to issue such Letters Patent in accordance herewith. I covenant that I am the lawful owner of the said application, inventions, and improvements, that the same are unencumbered, that no license has been granted to make, use, or vend the said inventions or improvements or any of them, and that I have the full right to make this assignment.

And for the consideration aforesaid, I agree jointly and individually that I

will communicate to said assignee or the representative thereof any facts known to me respecting said inventions and improvements, and will, upon request, but without expense to me, testify in any legal proceedings, sign all lawful papers, execute all divisional, reissue, continuation, renewal, and/or extension applications, make all rightful oaths, and generally do all other and further lawful acts, deemed necessary or expedient by said assignee or by counsel for said assignee, to assist or enable said assignee to obtain and enforce full benefits from the rights and interests herein assigned. This assignment shall be binding upon my heirs, executors, administrators, and/or assigns, and shall inure to the benefit of the heirs, executors, administrators, successors, and/or assigns, as the case may be, of said assignee.

Dated: Jang Hyuk Ahn

Oct. 29, 2002

Jang Hyuk AHN